

STGF19NC60WD

N-channel 600V - 7A - TO-220 Ultra fast PowerMESH™ IGBT

PRELIMINARY DATA

Features

Туре	V _{CES}	V _{CE(sat)} (max)@25°C	I _C @100°C
STGF19NC60WD	600V	< 2.5V	7A

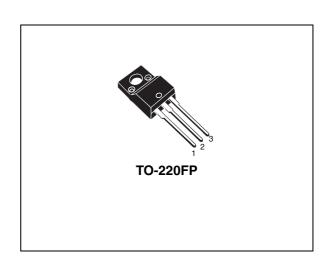
- High frequency operation
- Low C_{RES} / C_{IES} ratio (no cross-conduction susceptibility)
- Very soft ultra fast recovery antiparallel diode

Description

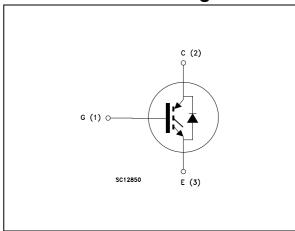
Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix "W" identifies a family optimized for very high frequency application.

Applications

- High frequency motor controls, inverters, UPS
- HF, SMPS and PFC in both hard switch and resonant topologies



Internal schematic diagram



Order code

Part number	Marking	Package	Packaging
STGF19NC60WD	GF19NC60WD	TO-220	Tube

Contents STGF19NC60WD

Contents

1	Electrical ratings 3
2	Electrical characteristics4
	2.1 Electrical characteristics (curves)
3	Test circuit
4	Package mechanical data11
5	Revision history

STGF19NC60WD Electrical ratings

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{CES}	Collector-emitter voltage (V _{GS} = 0)	600	V
I _C ⁽¹⁾	Collector current (continuous) at T _C = 25°C	14	Α
I _C ⁽¹⁾	Collector current (continuous) at T _C = 100°C	7	Α
I _{CL} ⁽²⁾	Collector current (pulsed)	35	Α
I _F	Diode RMS forward current at T _C = 25°C	12	Α
V _{GE}	Gate-emitter voltage	±20	V
P _{TOT}	Total dissipation at T _C = 25°C	32	W
T _{stg}	Storage temperature	- 55 to 150	
T _j	Operating junction temperature	- 33 10 130	°C

^{1.} Calculated according to the iterative formula:

$$I_{C}(T_{C}) = \frac{T_{JMAX}^{-T}C}{R_{THJ-C}^{\times V}CESAT(MAX)^{(T}C, \ I_{C})}$$

2. Vclamp=480V, Tj=150°C, R_G =10 Ω , V_{GE} =15V

Table 2. Thermal resistance

Symbol	Parameter	Value	Unit
Rthj-case	Thermal resistance junction-case max	4	°C/W
Rthj-amb	Thermal resistance junction-ambient max	62.5	°C/W

Electrical characteristics STGF19NC60WD

2 Electrical characteristics

(T_{CASE} =25°C unless otherwise specified)

Table 3. Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{BR(CES)}	Collector-emitter breakdown voltage	I _C = 1mA, V _{GE} = 0	600			٧
V _{CE(sat)}	Collector-emitter saturation voltage	V _{GE} = 15V, I _C = 12A V _{GE} = 15V, I _C =12A,Tc=125°C		2.1 1.8	2.5	V V
V _{GE(th)}	Gate threshold voltage	$V_{CE} = V_{GE}, I_{C} = 250 \mu A$	3.75		5.75	V
I _{CES}	Collector cut-off current (V _{GE} = 0)	V_{CE} = Max rating, T_{C} = 25°C V_{CE} = Max rating, T_{C} = 125°C			150 1	μA mA
I _{GES}	Gate-emitter leakage current (V _{CE} = 0)	V _{GE} = ±20V, V _{CE} = 0			±100	nA
9 _{fs}	Forward transconductance	V _{CE} = 15V _, I _C = 12A		10		S

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{ies} C _{oes} C _{res}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{CE} = 25V$, $f = 1MHz$, $V_{GE} = 0$		1180 130 26		pF pF pF
$egin{array}{c} Q_{ m g} \ Q_{ m ge} \ Q_{ m gc} \end{array}$	Total gate charge Gate-emitter charge Gate-collector charge	$V_{CE} = 390V$, $I_{C} = 5A$, $V_{GE} = 15V$, Figure 16		53 10 21		nC nC nC

Table 5. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	V_{CC} = 390V, I_{C} = 12A R_{G} = 10 Ω , V_{GE} = 15V, Figure 17		25 7 1600		ns ns A/µs
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	V_{CC} = 390V, I_{C} = 12A R_{G} = 10 Ω V_{GE} = 15V, T_{J} = 125°C Figure 17		25 8 1400		ns ns A/µs
t _r (V _{off}) t _d (_{off}) t _f	Off voltage rise time Turn-off delay time Current fall time	V_{CC} = 390V, I_{C} = 12A R_{G} = 10 Ω , V_{GE} = 15V, Figure 17		22 90 43		ns ns ns
t _r (V _{off}) t _d (_{off}) t _f	Off voltage rise time Turn-off delay time Current fall time	V_{CC} = 390V, I_{C} = 12A R_{G} = 10 Ω , V_{GE} = 15V, T_{J} = 125°C Figure 17		47 127 77		ns ns ns

Table 6. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
E _{on} ⁽¹⁾ E _{off} ⁽²⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	V_{CC} = 390V, I_{C} = 12A R_{G} = 10 Ω , V_{GE} = 15V, Figure 17		81 125 206		μJ μJ μJ
E _{on} ⁽¹⁾ E _{off} ⁽²⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	V_{CC} = 390V, I_{C} = 12A R_{G} = 10 Ω , V_{GE} = 15V, T_{J} = 125°C Figure 17		161 255 416		μJ μJ μJ

Eon is the turn-on losses when a typical diode is used in the test circuit in Figure 15 If the IGBT is offered
in a package with a co-pak diode, the co-pack diode is used as external diode. IGBTs & Diode are at the
same temperature (25°C and 125°C)

^{2.} Turn-off losses include also the tail of the collector current

Electrical characteristics STGF19NC60WD

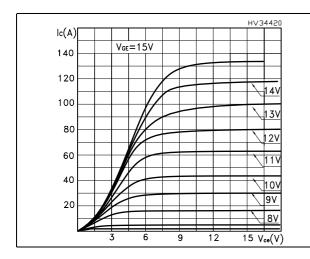
Table 7. Collector-emitter diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _f	Forward on-voltage	I _f = 12A I _f = 12A, Tj = 125°C		1.9 1.5	2.5	V V
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_f = 12A,V _R = 50V, Tj = 25°C, di/dt = 100 A/µs Figure 18		31 30 2		ns nC A
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	I _f = 12A,V _R = 50V, Tj =125°C, di/dt = 100A/μs <i>Figure 18</i>		59 102 4		ns nC A

2.1 Electrical characteristics (curves)

Figure 1. Output characteristics

Figure 2. Transfer characteristics



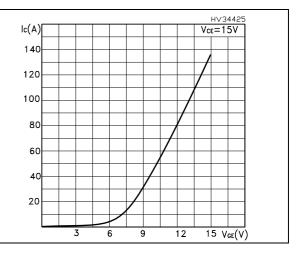
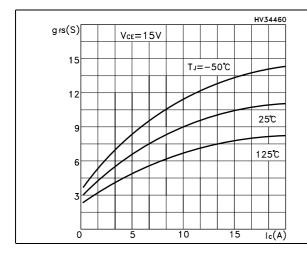


Figure 3. Transconductance

Figure 4. Collector-emitter on voltage vs temperature



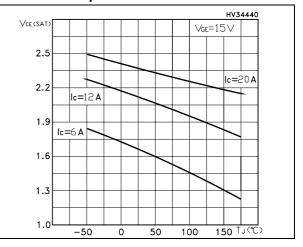
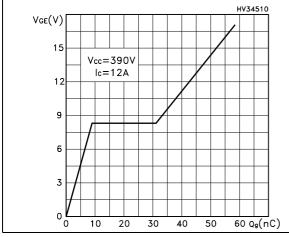
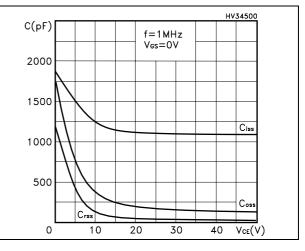


Figure 5. Gate charge vs gate-source voltage Figure 6. Capacitance variations





Electrical characteristics STGF19NC60WD

Figure 7. Normalized gate threshold voltage Figure 8. Collector-emitter on voltage vs vs temperature collector current

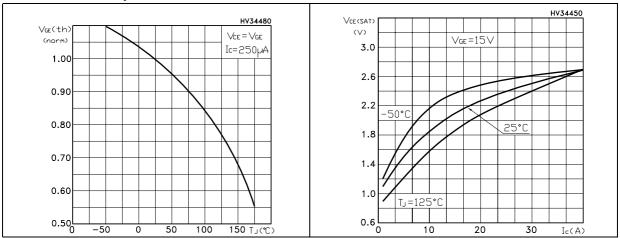


Figure 9. Normalized breakdown voltage vs Figure 10. Switching losses vs temperature temperature

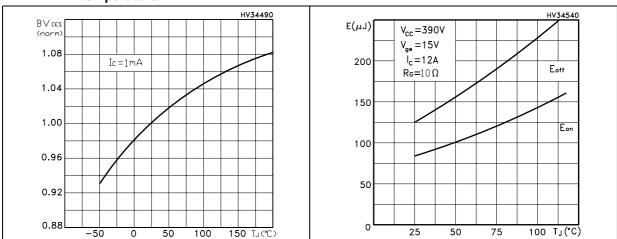
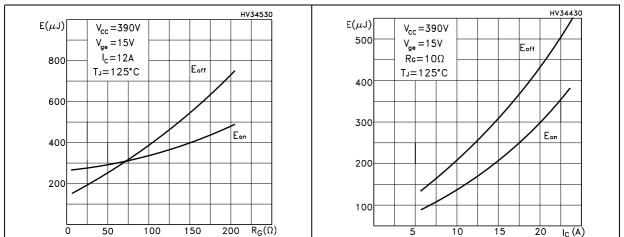


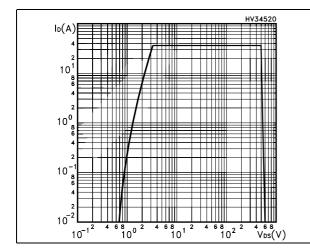
Figure 11. Switching losses vs gate resistance Figure 12. Switching losses vs collector current

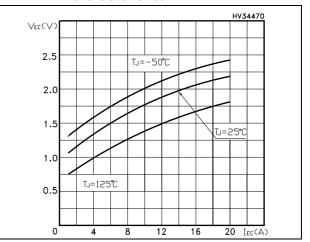


8/14

Figure 13. Turn-off SOA

Figure 14. Emitter-collector diode characteristics





Test circuit STGF19NC60WD

3 Test circuit

Figure 15. Test circuit for inductive load switching

Figure 16. Gate charge test circuit

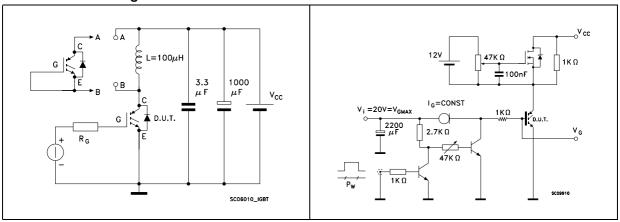
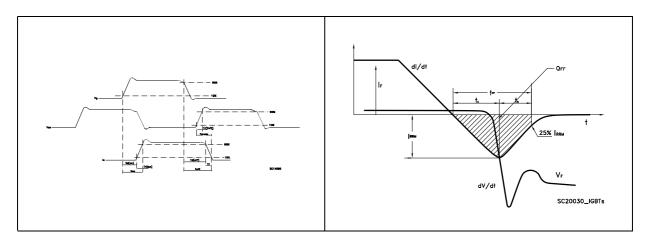


Figure 17. Switching waveform

Figure 18. Diode recovery time waveform



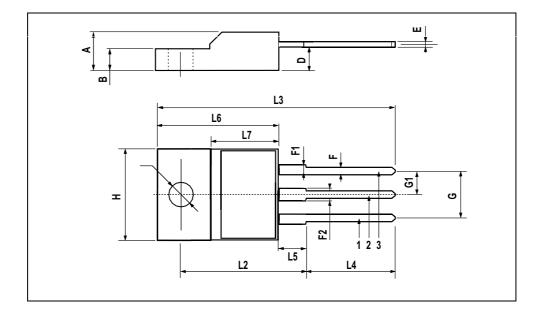
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

11/14

TO-220FP MECHANICAL DATA

DIM.		mm.			inch	
DIIVI.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
Α	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
Е	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



STGF19NC60WD Revision history

5 Revision history

Table 8. Revision history

Date	Revision	Changes
13-Oct-2006	1	Initial release.
08-May-2007	2	Corrected value on Table 1, Table 2

13/14

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